

Title (en)

COPPER ALLOY FOR ELECTRONIC MATERIAL AND METHOD OF MANUFACTURE FOR SAME

Title (de)

KUPFERLEGIERUNG FÜR EIN ELEKTRONISCHES MATERIAL UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

ALLIAGE DE CUIVRE POUR UN MATÉRIEL ÉLECTRONIQUE ET PROCÉDÉ DE FABRICATION DE CE DERNIER

Publication

EP 2551384 A4 20170719 (EN)

Application

EP 11759455 A 20110323

Priority

- JP 2010066397 A 20100323
- JP 2011057026 W 20110323

Abstract (en)

[origin: EP2551384A1] There is provided a copper alloy for electronic material which exhibits excellent plating uniformity. A copper alloy for electronic material, wherein, when its cross section parallel to a rolling direction is observed by SIM, an area ratio of amorphous structure and crystal grains having a grain size of less than 0.1 μ m at a depth range of 0.5 μ m or less from the surface is 1% or less, and a ratio of the number of crystal grains having a grain size of at least 0.1 μ m and less than 0.2 μ m to the overall number of crystal grains having a grain size of at least 0.1 μ m at a depth range of 0.2-0.5 μ m from the surface is 47.5% or more.

IPC 8 full level

C25D 5/34 (2006.01); **B24B 37/00** (2012.01); **C22C 9/00** (2006.01); **C22C 9/01** (2006.01); **C22C 9/02** (2006.01); **C22C 9/04** (2006.01); **C22C 9/05** (2006.01); **C22C 9/06** (2006.01); **C22C 9/10** (2006.01); **C25D 7/00** (2006.01); **C25D 7/06** (2006.01)

CPC (source: EP KR US)

C22C 9/02 (2013.01 - EP KR); **C22C 9/06** (2013.01 - EP KR); **C25D 5/34** (2013.01 - EP KR); **C25D 7/00** (2013.01 - EP KR US); **C25D 7/06** (2013.01 - EP); **C25D 7/0614** (2013.01 - KR)

Citation (search report)

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Designated contracting state (EPC)

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DOCDB simple family (publication)

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DOCDB simple family (application)

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